

描述 / Descriptions

SOT-363 塑封封装肖特基二极管。
Schottky Diode in a SOT-363 Plastic Package.

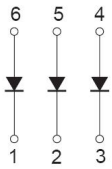
特征 / Features

低正向压降，可忽略的反向恢复时间。无卤产品。
Low positive pressure drop, can ignore the reverse recovery time. HF Product.

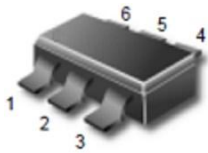
用途 / Applications

肖特基二极管。
Schottky diode.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN: See Equivalent Circuit.

放大及印章代码 / h_{FE} Classifications & Marking

| | |
|---------|----------|
| Model | SD103ATW |
| Marking | KLL |

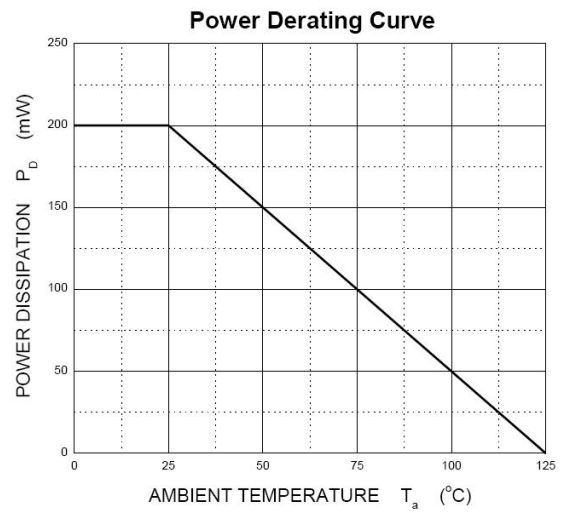
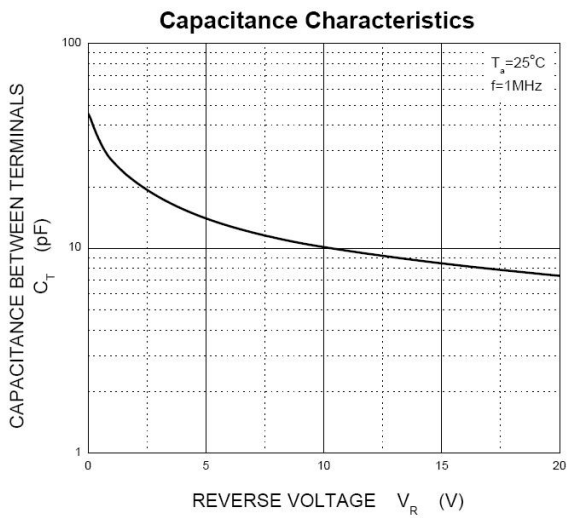
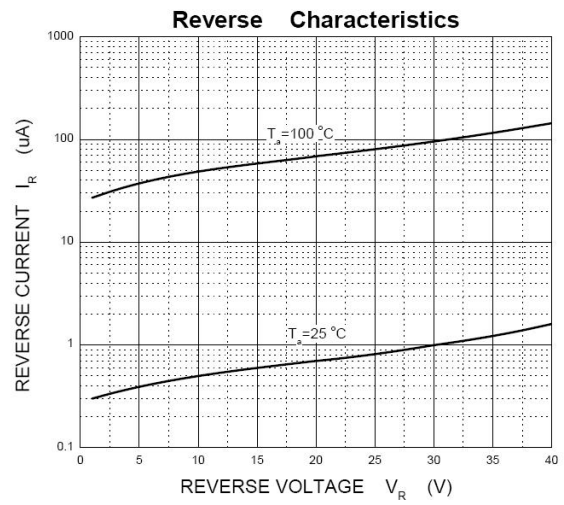
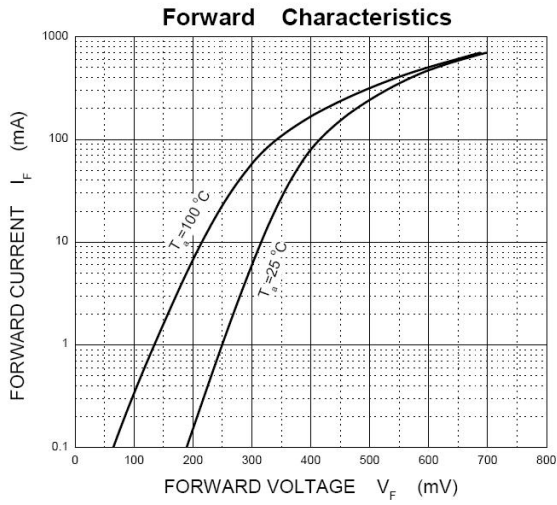
极限参数 / Absolute Maximum Ratings(Ta=25°C)

| 参数 Parameter | 符号 Symbol | 数值 Rating | 单位 Unit |
|---|---------------------------------|--------------|------------|
| | | SD103ATW | |
| Peak Repetitive Peak Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_R | 40 | V |
| RMS Reverse Voltage | $V_{R(RMS)}$ | 28 | V |
| Average Rectified Current | I_O | 175 | mA |
| Forward Continuons Current | I_{FM} | 350 | mA |
| Non-repetitive Peak Forward Surge Current@t=8.3ms | I_{FSM} | 2 | A |
| Power Dissipation | P_D | 200 | mW |
| Typical Thermal Resistance Junction to Ambient | $R_{\theta JA}$ | 500 | °C/W |
| Junction temperature | T_j | 125 | °C |
| Junction and Storage Temperature Range | T_{STG} | -55~125 | °C |

电性能参数 / Electrical Characteristics(Ta=25°C)

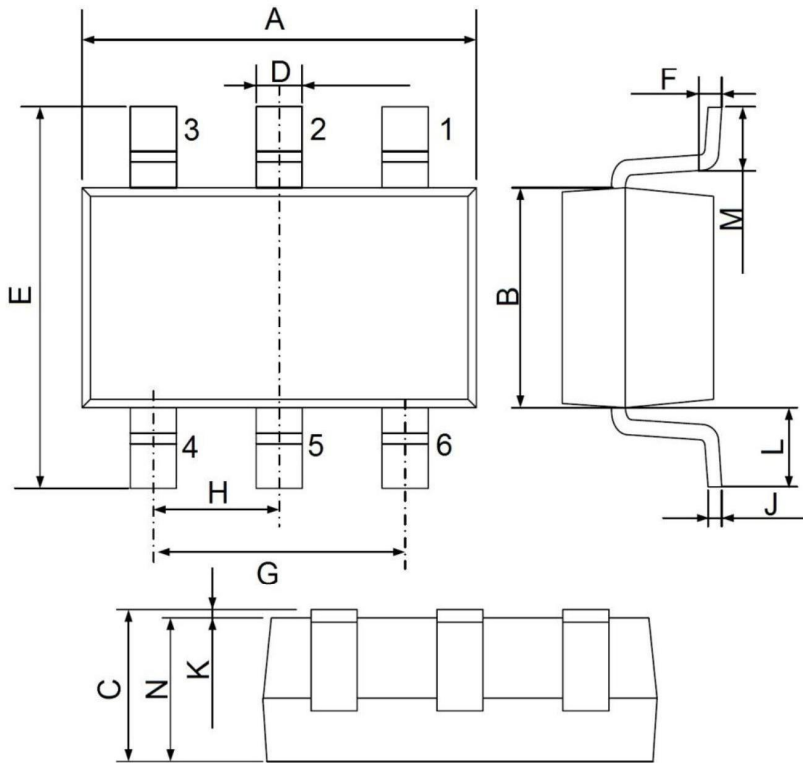
| 参数 Parameter | 符号 Symbol | 测试条件 Test Conditions | 最小值 Min | 典型值 Typ | 最大值 Max | 单位 Unit |
|-------------------------------|--------------|--|------------|------------|------------|------------|
| Reverse breakdown voltage | $V_{(BR)}$ | $I_R=100\mu A$ | 40 | | | V |
| Forward voltage | V_F | $I_F=20mA$ | | | 0.37 | V |
| | | $I_F=100mA$ | | | 0.50 | |
| Reverse current | I_R | $V_R=10V$ | | | 2.0 | μA |
| | | $V_R=30V$ | | | 5.0 | |
| Capacitance between terminals | C_T | $V_R=0V$ $f=1.0MHZ$ | | 50 | | pF |
| Resistance Range Time | t_{rr} | $I_F=I_R=200mA$ $I_{rr}=0.1 \times I_R$ $R_L=100\Omega$ | | 10 | | ns |

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

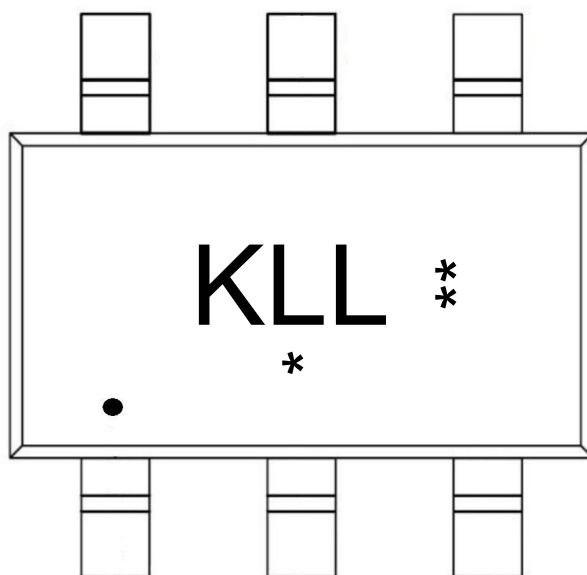
SOT-363-6L



UNIT: mm

| DIM | MIN | MAX |
|-----|------------|------|
| A | 2.00 | 2.20 |
| B | 1.15 | 1.35 |
| C | 0.90 | 1.10 |
| D | 0.15 | 0.35 |
| E | 1.95 | 2.25 |
| F | 0.20 Typ. | |
| G | 1.20 | 1.40 |
| H | 0.65 Typ. | |
| J | 0.08 | 0.15 |
| K | 0.00 | 0.10 |
| L | 0.525 Ref. | |
| M | 0.26 | 0.46 |
| N | 0.90 | 1.10 |

印章说明 / Marking Instructions



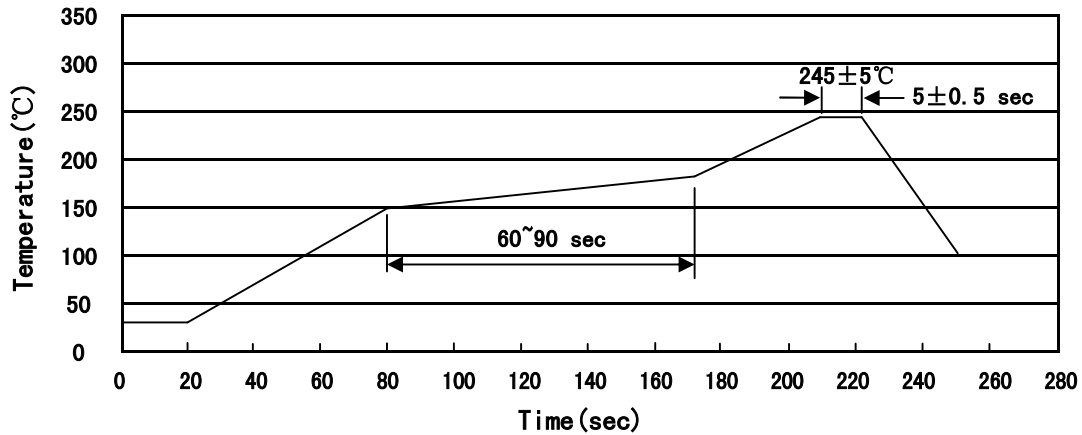
说明：

- ： 为“1”脚
- KLL： 为型号代码
- ***： 为生产批号代码，随生产批号变化

Note:

- ： “1” Pin
- KLL： Product Type Code
- ***： Lot No. Code, code change with Lot No.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C 时间：10±1 sec. Temp.:260±5°C Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

| Package Type 封装形式 | Units 包装数量 | | | | | Dimension 包装尺寸 (unit: mm3) | | |
|----------------------|--------------------|-------------------------|------------------------|------------------------------|------------------------|----------------------------|-------------|-------------|
| | Units/Reel 只/卷盘 | Reels/Inner Box 卷盘/盒 | Units/Inner Box 只/盒 | Inner Boxes/Outer Box 盒/箱 | Units/Outer Box 只/箱 | Reel | Inner Box 盒 | Outer Box 箱 |
| SOT-363 | 3,000 | 10 | 30,000 | 6 | 180,000 | 7" ×8 | 180×120×180 | 390×385×205 |

使用说明 / Notices